



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. MUSSER

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME
AND THE LIKE

RECEIVED
FEB 19 2003
TC 1700

SUBMISSION OF DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

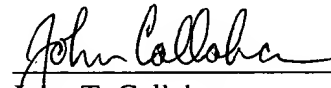
Submitted herewith please find 1 sheet of drawing in compliance with 37 C.F.R. § 1.84.

The Examiner is respectfully requested to acknowledge receipt of this drawing.

The submitted drawing incorporates the proposed drawing changes approved in Paper
No. 9.

Respectfully submitted,

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860


John T. Callahan
Registration No. 32,607

WASHINGTON OFFICE



23373

PATENT TRADEMARK OFFICE

Date: February 12, 2003